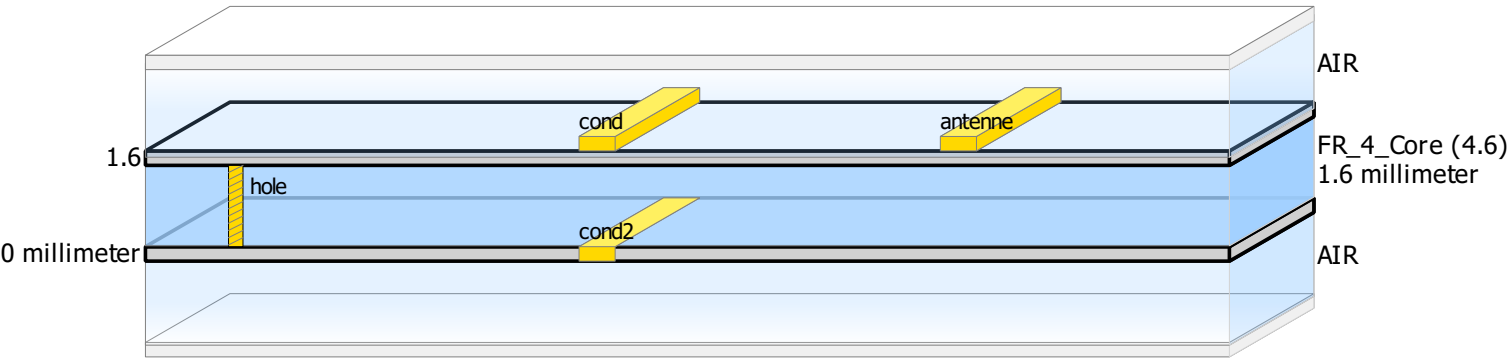


Substrate Layers

	Type	Name	Material	Thickness	Er	TanD
	Dielectric		AIR			
1	Conductor Layer	antenne (39)	Copper	35 um		
1	Conductor Layer	cond (1)	Copper	35 um		
	Dielectric		FR_4_Core	1.6 mm	4.6	0.01
2	Conductor Layer	cond2 (2)	Copper	35 um		
	Dielectric		AIR			



Substrate Vias

	Type	Name	Top	Bottom	Material	Er	TanD
	Conductor Via	hole (5)	cond (1)	cond2 (2)	Copper		